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WHAT IS CLAIMED IS:

1. A circuit board comprising a conductive pattern section with a pattern formed on a conductive layer provided on a board main body,

5 wherein at least two bonding positions corresponding to bumps of a part mounted by ultrasonic bonding strike are defined in said conductive pattern section,

10 wherein one of an isolated notch part and recess is formed in the conductive layer in the proximity of at least one bonding position.

2. The circuit board as claimed in claim 1, wherein said notch part or the recess is formed extending in a direction traversing an ultrasonically vibrating direction of the ultrasonic bonding.

15 3. The circuit board as claimed in claim 1, wherein said notch part or the recess partially narrows said conductive pattern section to form a narrow pattern part.

20 4. A circuit board comprising a conductive pattern section with a pattern formed on a conductive layer provided on a board main body,

wherein at least two bonding positions corresponding to bumps of a part mounted by ultrasonic bonding strike are defined in said conductive pattern section,

wherein the conductive layer in the proximity of at least one bonding position, one of a notch part and a recess extending from a margin of said conductive pattern section to an inside thereof and reaching the proximity of the bonding 5 position is formed.



5. The circuit board as claimed in claim 4, wherein said notch part or the recess is formed extending in a direction traversing an ultrasonically vibrating direction of the ultrasonic bonding.

10 6. The circuit board as claimed in claim 4, wherein said notch part or the recess partially narrows said conductive pattern section to form a narrow pattern part.

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